

<b>Notice of References Cited</b>	Application/Control No. 09/851,905	Applicant(s)/Patent Under Reexamination SONDERMAN ET AL.	
	Examiner Ryan A. Jarrett	Art Unit 2125	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Smith, T.H., Boning, D.S., Stefani, J. and Butler, S.W. "Run by Run Advanced Process Control of Metal Sputter Deposition". IEEE Transactions on Semiconductor Manufacturing 11.2 (1998): 276-284
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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